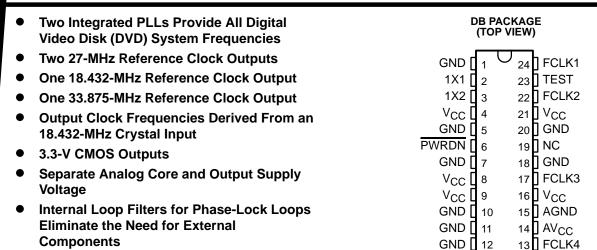
SCAS558B - DECEMBER 1995 - REVISED OCTOBER 1996



NC - No internal connection

### description

The CDC9171 is a high-performance clock synthesizer that generates the required clock signals needed for a DVD system.

The CDC9171 generates all output frequencies from an 18.432-MHz crystal. The 18.432-MHz (FCLK1) reference clock output is buffered from the integrated oscillators. Two integrated phase-lock loops (PLL) synthesize the 27-MHz (FCLK2, FCLK3) and the 33.868-MHz (FCLK4) reference clock outputs from the 18.4320-MHz crystal. The oscillator and PLLs can be bypassed in the TEST mode. When TEST is high, input 1X1 is buffered to all outputs.

All clock outputs provide low-jitter clock signals for reliable clock operation. PWRDN is used to disable the PLLs and output buffers. When low, PWRDN disables the integrated PLLs and forces all outputs to a logic-low state.

Because the CDC9171 is based on PLL circuitry, it requires a stabilization time to achieve phase lock of the PLL. This stabilization time is required following power up and application of a fixed-frequency, fixed-phase signal at the 1X1 input and upon activation, following the transition of PWRDN to a logic-high state.

#### **FUNCTION TABLE**

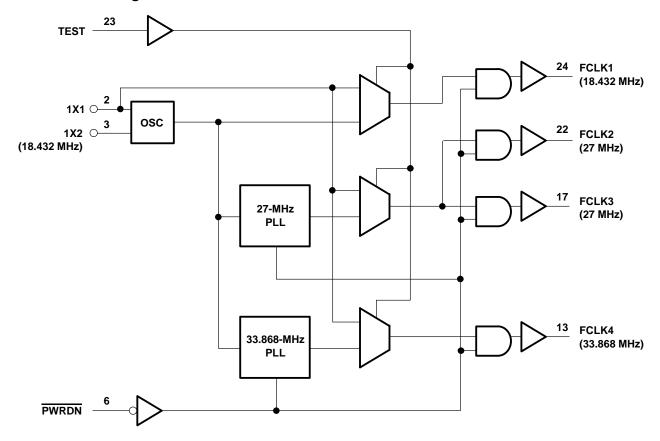
INPUTS			OUTPUTS				
PWRDN	TEST	1X1	FCLK1	FCLK(2-3)	FLCK4		
L	Х	Х	L	L	L		
Н	L	18.432 MHz	18.432 MHz	27 MHz	33.868 MHz		
Н	Н	L	L	L	L		
Н	Н	Н	Н	Н	Н		



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### functional block diagram



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Voltage range applied to any output in the high state or power-off state, V <sub>O</sub> )	0.5 V to $V_{CC}$ + 0.5 V
Current into any output in the low state, I <sub>O</sub>	±35 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>I</sub> < 0)	±50 mA
Maximum power dissipation at T <sub>A</sub> = 55°C (in still air) (see Note 2)	0.65 W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input clamp-current ratings are observed.
  - 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.



### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	3	3.6	V
VI	Input voltage (PWRDN only)	0	5.5	V
VIH	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
ІОН	High-level output current		-8	mA
loL	Low-level output current		8	mA
TA	Operating free-air temperature	0	70	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION	•	T <sub>A</sub> = 25°C		MIN MAX		UNIT	
PARAMETER		TEST CONDITION	3	MIN TYP MAX			IVIIIN	WAX	UNII
VIK	V <sub>CC</sub> = 3 V,	I <sub>I</sub> = -18 mA				-1.2		-1.2	V
VOH	V <sub>CC</sub> = 3 V,	I <sub>OH</sub> = -8 mA		2.4			2.4		V
V <sub>OL</sub>	$V_{CC} = 3 V$ ,	$I_{OL} = 8 \text{ mA}$				0.4		0.4	V
II <sup>†</sup>	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND				±1		±1	μΑ
1	V <sub>CC</sub> = 3.6 V,	I <sub>O</sub> = 0	Outputs active (PWRDN = H)		20	35		35	A
'cc	$V_I = V_{CC}$ or GND		Outputs low (PWRDN = L)		5	10		10	mA
C <sub>i</sub> †	V <sub>I</sub> = 3 V or 0		•		7				pF
Co	V <sub>O</sub> = 3 V or 0				8				pF

<sup>†</sup> Except for crystal input (1X1)

# timing requirements over recommended ranges of supply voltage and operating free-air temperature

		MIN	MAX	UNIT
Ctabilization time †	After PWRDN ↑		5	<b>m</b> o
Stabilization time <sup>‡</sup>	After power up		5	ms

<sup>&</sup>lt;sup>‡</sup> Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at 1X1.

## switching characteristics over recommended free-air temperature range for 3-V outputs (see Figure 1)§

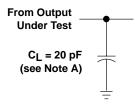
PARAMETER		V <sub>CC</sub> = 3.3 V, T <sub>A</sub> = 25°C		V <sub>CC</sub> = 3 V to 3.6 V, T <sub>A</sub> = 0°C to 70°C		UNIT
		MIN	MAX	MIN	MAX	
Jitter	FCLK1				±200	ps
	All other outputs				±250	
Duty cycle	Any output			45%	55%	
t <sub>r</sub> ¶	Any output ( $C_L = 20 \text{ pF}$ )				2.5	ns
t <sub>f</sub> ¶	Any output (C <sub>L</sub> = 20 pF)				2.5	ns

<sup>§</sup> Specifications are applicable only after the PLL stabilization time has elapsed.

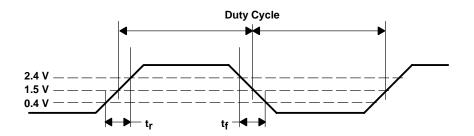
 $<sup>\</sup>P$  Rise and fall times are characterized using the test circuit shown in Figure 1.



#### PARAMETER MEASUREMENT INFORMATION



**LOAD CIRCUIT** 



NOTES: A.  $C_L$  inlcudes probe and jig capacitance. B. The outputs are measured one at a time with one transition per measurement.

Figure 1. Voltage Waveform and Load Circuit

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